



VMDSEMI

**VUDD002R150NC**

**Datasheet**



VMDSEMI

## General Summary

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
20V	15mΩ@4.5V	12A
	18mΩ@2.5V	
	30mΩ@1.8V	

## Symbol

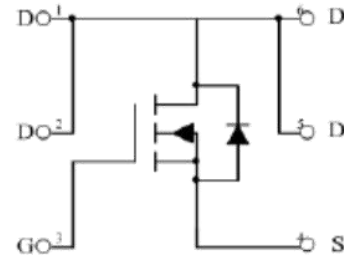


Figure 1 Symbol of VUDD002R150NC

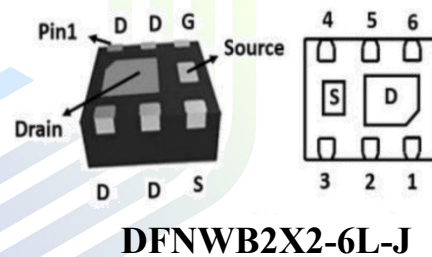
## Features

- Small package DFNWB2×2-6L-J
- Trench FET Power MOSFET
- N-Channel Switch Low  $R_{DS(ON)}$
- Operated at Low Logic Level Gate Drive

## Application

- Interfacing switching
- Load Switch for Portable Applications
- PWM Switch

## Package Type



**DFNWB2X2-6L-J**

Figure 2 Package Type of VUDD002R150NC

## Ordering Information

Product Name	Package
VUDD002R150NC	DFNWB2X2-6L-J

**Absolute Maximum Ratings** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	20	V
Gate-Source Voltage	$V_{GSS}$	$\pm 10$	V
Continuous Drain Current <sup>Note1,2</sup>	$I_D$	12	A
Pulsed Drain Current	$I_{DM}$	40	A
Max Power Dissipation <sup>Note1</sup>	$P_D$	0.75	W
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note1,2</sup>	$R_{\theta JA}$		167		$^\circ\text{C/W}$



VMDSEMI

**Electrical Characteristics**  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=16V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 10V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	0.7	1.0	V
Static Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=3A$		10	15	mΩ
		$V_{GS}=2.5V, I_D=3A$		14	18	
		$V_{GS}=1.8V, I_D=3A$		23	30	
Forward tranconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS}=4V, I_D=10A$	10			S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=4V$		1900		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		700		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		480		pF
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS}=4V$		20		nC
Gate-source Charge	$Q_{gs}$	$V_{GS}=5V$		2.5		
Gate-drain Charge	$Q_{gd}$	$I_D=10A$		6.5		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=4V$		15		ns
Rise Time	$t_r$	$V_{GEN}=4.5V$		10		
Turn-off Delay Time	$t_{d(off)}$	$R_L=0.4\Omega$		70		
Fall Time	$t_f$	$R_G=1\Omega$		15		
<b>Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=1A$			1.2	V
Diode Forward Current	$I_S$				12	A

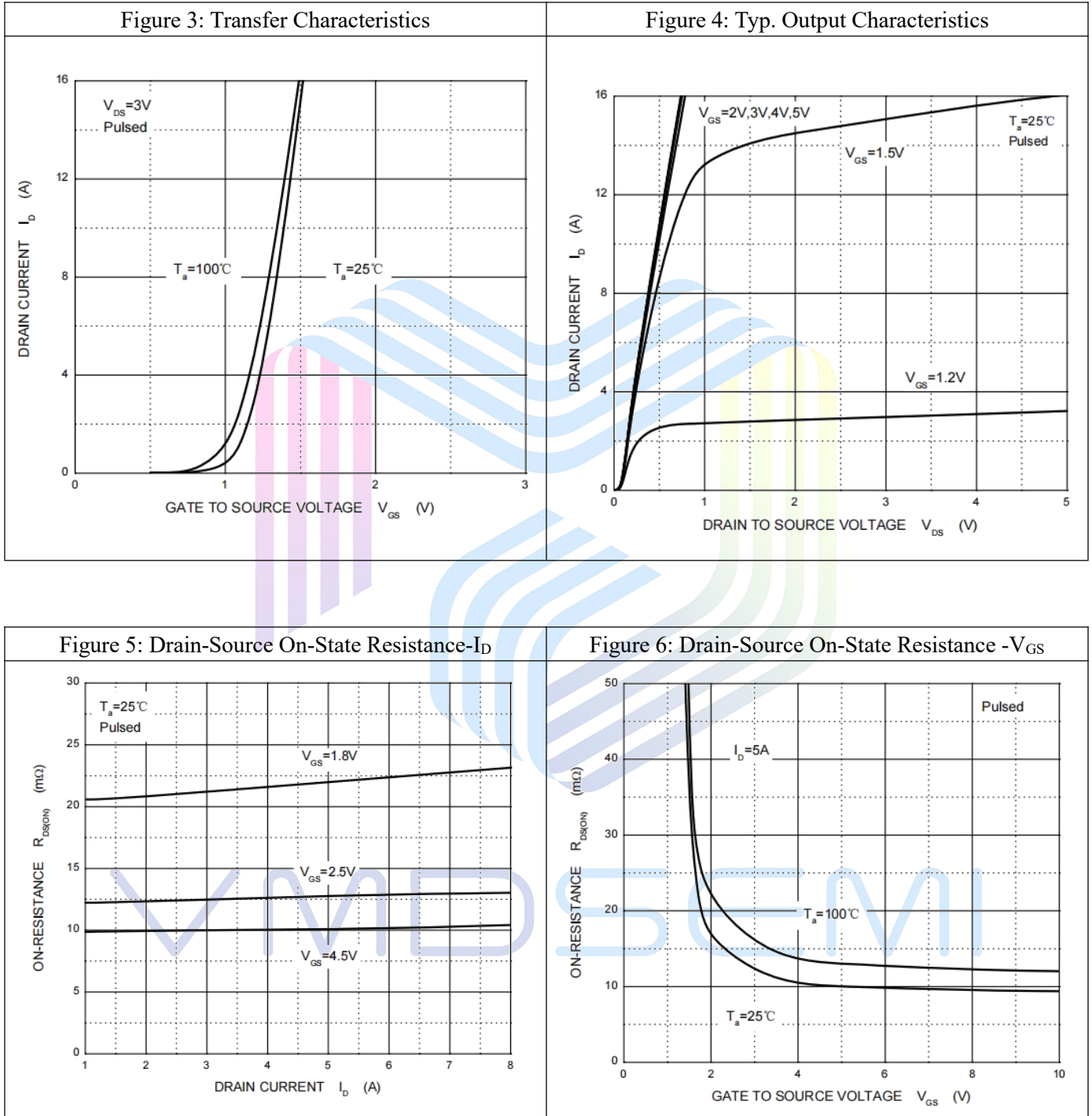
Notes :

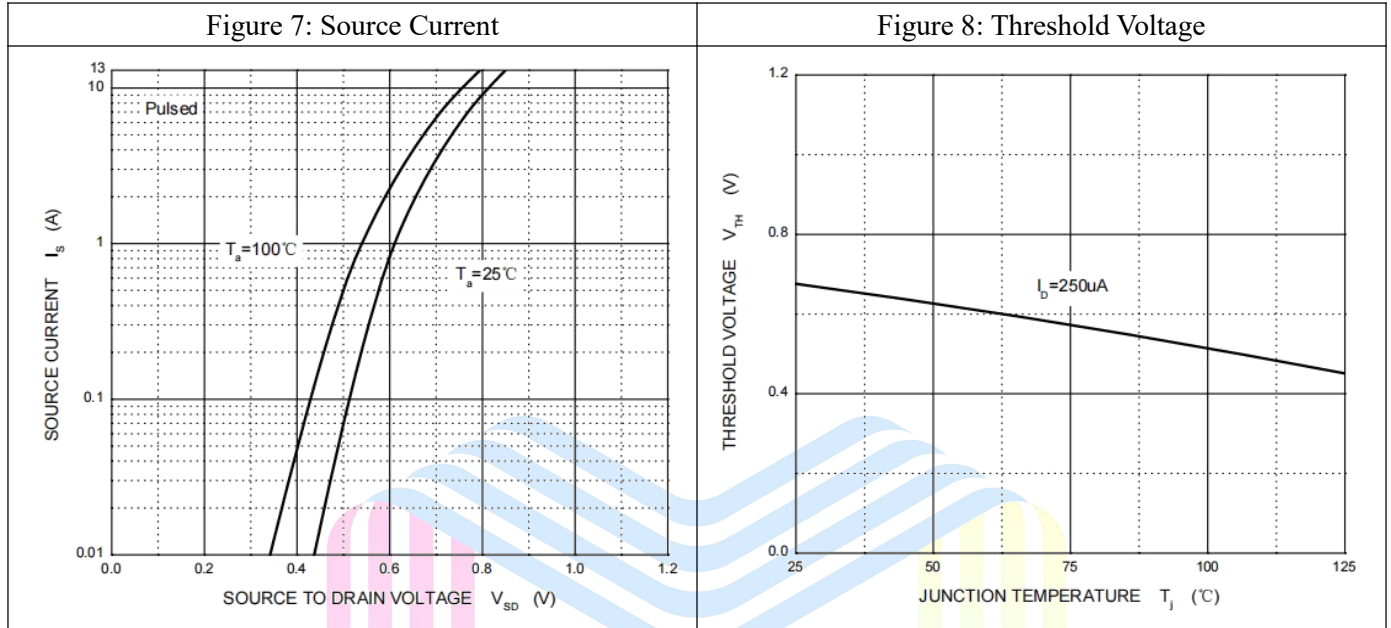
1.  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR4 board with 1oz. single side copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

2.  $R_{\theta JA}$  is measured in the steady state

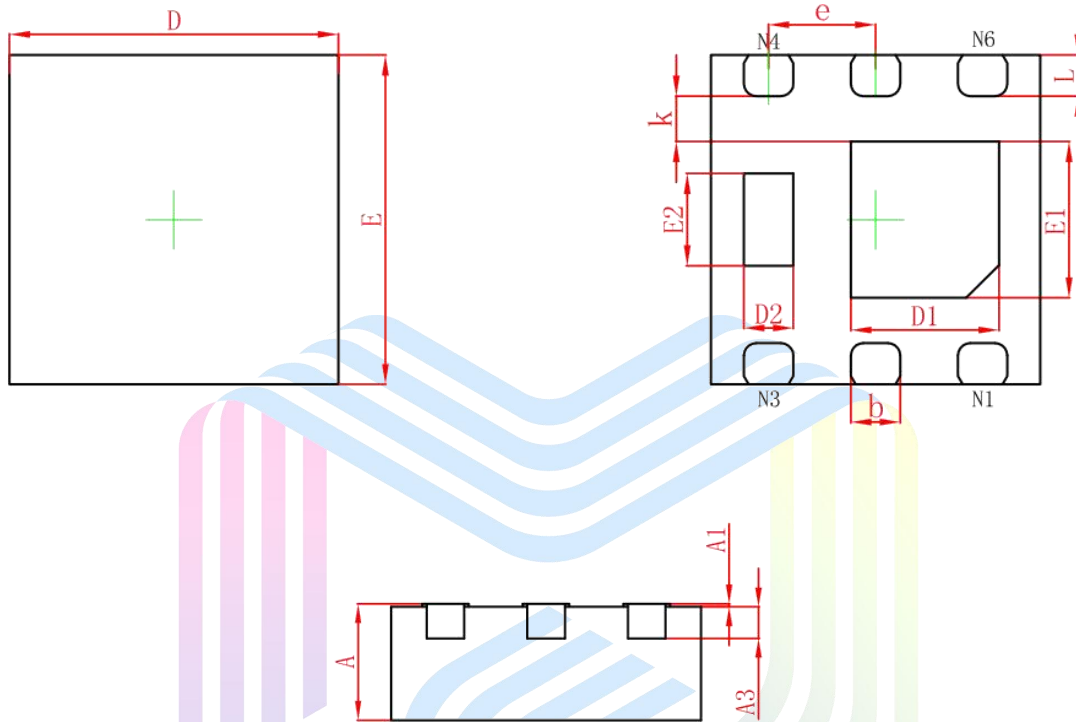
3. Pulse test : Pulse width  $\leq 380\mu s$ , duty cycle  $\leq 2\%$ .

## Typical Performance Characteristics





VMDSEMI

**Mechanical Dimensions:**
**DFNWB2×2-6L-J Package Information**


Symbol	Dimensions (Unit:mm)		Dimensions (Unit:inch)	
	Min.	Max.	Min.	Max.
A	0.700	0.800		0.032
A1	0.000	0.050	0.000	0.002
A3	0.203REF		0.008REF	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN		0.008MIN	
b	0.250	0.350	0.010	0.014
e	0.650TYP		0.026TYP	
L	0.174	0.326	0.007	0.013

## NOTICE

Hangzhou VMD Semiconductor Co., Ltd (VMD) reserves the right to make changes without notice in order to improve reliability, function or design and to discontinue any product or service without notice. Customers should obtain the latest relevant information before orders and should verify that such information is current and complete. All products are sold subject to VMD's terms and conditions supplied at the time of order acknowledgement.

VMD, its affiliates, agents, and employees, and all persons acting on its or their behalf, disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

VMD disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify VMD's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

VMD warrants performance of its hardware products to the specifications at the time of sale, testing, reliability and quality control are used to the extent VMD deems necessary to support this warrantee. Except where agreed upon by contractual agreement, testing of all parameters of each product is not necessarily performed.

VMD does not assume any liability arising from the use of any product or circuit designs described herein. Customers are responsible for their products and applications using VMD's components. To minimize risk, customers must provide adequate design and operating safeguards.

VMD does not warrant or convey any license to any intellectual property rights either expressed or implied under its patent rights, nor the rights of others. Reproduction of information in VMD's data sheets or data books is permissible only if reproduction is without modification or alteration. Reproduction of this information with any alteration is an unfair and deceptive business practice.

VMD is not responsible or liable for such altered documentation. Resale of VMD's products with statements different from or beyond the parameters stated by VMD for that product or service voids all express or implied warrantees for the associated VMD product or service and is an unfair and deceptive business practice.

All Rights Reserved.







**Via-Media Semiconductor Limited Company**

<http://www.vmdsemi.com>

**Main Sites:**

**- Headquarters**

Hangzhou Via-Media Semiconductor Co., LTD.  
1305-1306, Building 71, No. 90, Wensan Road, Xihu  
District, Hangzhou, Zhejiang Province, P.R. China  
Tel: +86-0571-8515 0563

**- Chengdu Office**

Chengdu Winhi Semiconductor Co., LTD.  
Floor 15, Building 5, No. 171, Hele 2<sup>nd</sup> Street,  
Chengdu, Sichuan Province, P.R. China  
Tel: +86-028-8505 0771

**- Shanghai**

Shanghai R&D Center.  
1506~1508, Xinyin Building, 888 Yishan Road,  
Shanghai, P.R of China  
Tel: +86- 021-54201999

**- Shenzhen**

Shenzhen Sales office  
Room 4A15, Block AB, Tianxiang Building,  
Chegongmiao , Futian District, Shenzhen, P.R of China  
Tel: +86-0755- 82570682

**- Xi'an**

Xi'an R&D Center  
1703B, Building A, Greenland Center, Jinye Road,  
High-Tech Zone, Xi'an, Shaanxi, P.R of China